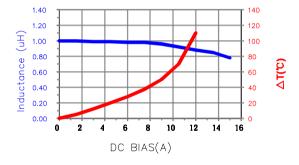
MGV06021R0M-10

PHYSICAL DIMENSIONS:

Α	7.30	±	0.50
В	6.70	<u>±</u>	0.30
С	2.00	±	0.30
D	2.90	±	0.30
Ε	1.60	<u>±</u>	0.50

LAND PATTERNS FOR REFLOW SOLDERING

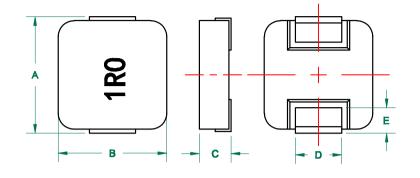




ELECTRICAL SPECIFICATION @ 25°C

	Min	Nom	Max	
INDUCTANCE (uH) L @ 100 KHz/0.25V ± 20%	0.80	1.00	1.20	
DCR (Ω)			0.0183	

Saturation Current ³ Isat (A)	14.00
Temperature Rise Current Irms ⁴ (A)	7.00









NOTES: UNLESS OTHERWISE SPECIFIED

- 1.COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2.OPERATION TEMPERATURE RANGE:
 - -40°C~+125°C (INCLUDING SELF-HEATING).
- 3.SATURATION CURRENT Isat IS DEFINED AS MAXIMUM AMOUNT OF CURRENT BY WHICH INDUCTANCE WILL DROP BY TYPICAL VALUE OF 25% OF INITIAL INDUCTANCE (Ta=25±5°C).
- 4.TEMPERATURE RISE CURRENT (Irms): DC CURRENT THAT CAUSES THE TEMPERATURE RISE ($\Delta T \leq 40^{\circ}$ C) FROM 25°C AMBIENT.

	DIMENSIONS ARE IN mm. This print is the property of Laird								
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L					copies shall be made without the written consent of Laird Tech. All				
L					rights to design or invention are reserved.				
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